

Thermal shock test method

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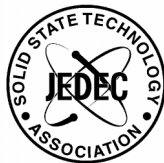
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INTERNATIONAL
ELECTROTECHNICAL
COMMISSION



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JEDEC STANDARD

Test Method A106-A

Thermal Shock

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ELECTRONIC INDUSTRIES ASSOCIATION
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Withdrawing

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

THERMAL SHOCK TEST METHOD

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IEC-PAS 62185 was submitted by JEDEC and has been processed by IEC technical committee 47: Semiconductor devices.

The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:

Draft PAS	Report on voting
47/1458/PAS	47/1491/RVD

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**TEST METHOD A106-A
THERMAL SHOCK**

(From Council Ballot JCB-94-51 formulated under the cognizance of JC-14.1 Committee on Reliability Test Methods for Packaged Devices)

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